

GSP-2933/RX

Kat.-Nr. 3062

Special Flux for wave-, selective-, hand-soldering
(WEEE/RoHS-conform)

Typ ISO 9454: 1231 (1.2.3.A)

DIN-EN 61190-1-1 (J-STD-004): (IEC RE/L0) / (NO CLEAN)



GSP-2933/RX is a flux of the latest generation. It is a high performance NO-CLEAN flux based on alcohol with di-carboxylic acid activator complex and synthetic resin. This flux was used for selective u. Wellenlötprozesse, as well as for dip soldering process and cable-strands-tining developed. The application can be carried out by any usual application method (inclusive foams).

Technical specifications:

Appearance:	Colorless- reddish, clear liquid	Two white plastic jugs of GSP-2933/RX flux, one smaller and one larger, with labels.
Solids content:	2,9% (2,8 – 3,1 %)	
Density at 20 ° C:	0,799 (+/- 0,005) g/ml	
Acid number (activity):	25 - 29 mg KOH/g	
Activators:	(Di-) carboxylic acid complex with synthetic resin (Resin)	
Solvent:	Short chain alcohols	
Flash point:	12 °C (cc)	
Storage conditions (recommended):	Store in a cool and dry place, fire protection u. Ex-protective regulations must be observed.	
Working temperature:	At room temperature (usually 20-25 ° C)	

Additional information on the ingredients (hazardous substances), safe handling, storage, transport and disposal can be found in the current safety data sheet (SDS, SDS, MSDS).

Recommendations for the processing of this flux:

This flux is very versatile, both in wave soldering and special applications are good results. The generally valid rule to choose applied flux quantities as low as possible, also applies to this product.

Spray fluxing: When dosing, the amount of flux initially to 15 - 30 ml / min. Adjust the uniform flux distribution on the printed circuit board (if necessary test with thermal paper) and then correct to the optimum amount.

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Foam fluxing (foam flux application): The compressor output should be even, so that a stable and fine-pored foam crown is achieved. When compressed air supply from the network, the interposition of a water and Öabscheiders and at least one pressure reducer is required. Optimal is an air pressure in the range of 0.6 - 0.8 bar. Fine-pored foam stones or pipes (10-20 µm) facilitate foam flow. The nozzle slot should not be more than 15 mm. Side-mounted, perforated support plates promote the stability of the foam. After the foam has been flown, it is recommended to blow off with air to evenly distribute the flux and retain excess amounts.

Density correction: The Flux Thinner "K-113", cat.-no. 1003, available.

Preheating: For "simple" PCBs, a preheat temperature of 80 - 110 ° C, recommended for "more complex" boards from 100 - 130 ° C on the top side of the PCB. The use can be made both in leaded and lead-free solder systems.

Storage:

The shelf life when properly stored between 15 and 25 ° C is 12 months.

Standard packing units (domestic):

Canisters (jerry cans 3H1) with 5, 10 and 20 liters
- other containers available on request

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